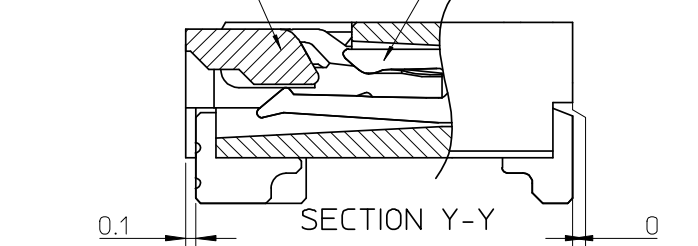
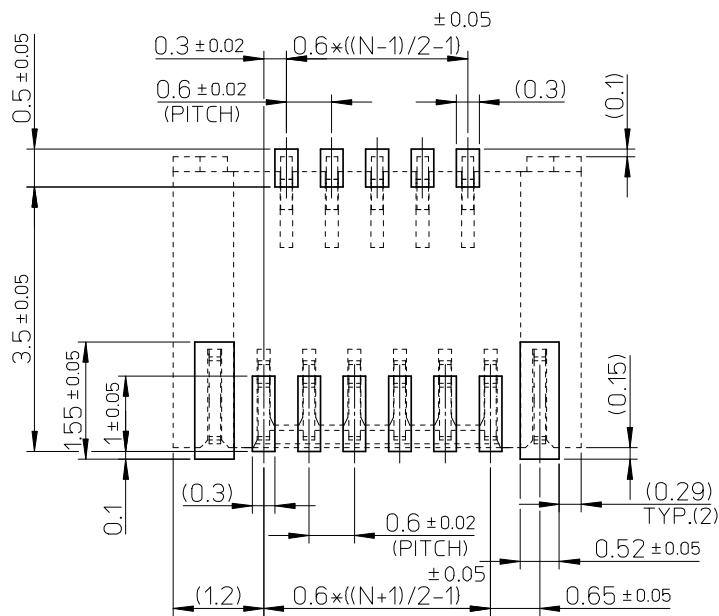


15.6	14.4	15.0	17.4	501912-5190	501912-5110	51
14.4	13.2	13.8	16.2	501912-4790	501912-4710	47
13.8	12.6	13.2	15.6	501912-4590	501912-4510	45
12.6	11.4	12.0	14.4	501912-4190	501912-4110	41
12.0	10.8	11.4	13.8	501912-3990	501912-3910	39
11.4	10.2	10.8	13.2	501912-3790	501912-3710	37
10.8	9.6	10.2	12.6	501912-3590	501912-3510	35
10.2	9.0	9.6	12.0	501912-3390	501912-3310	33
8.4	7.2	7.8	10.2	501912-2790	501912-2710	27
7.8	6.6	7.2	9.6	501912-2590	501912-2510	25
7.2	6.0	6.6	9.0	501912-2390	501912-2310	23
6.6	5.4	6.0	8.4	501912-2190	501912-2110	21
4.8	3.6	4.2	6.6	501912-1590	501912-1510	15
D	C	B	A	EMBOSSED-TAPE PKG ORDER No.	MATERIAL No.	CIRCUIT
MODEL No. 501912-**10						



REVISED EC NO: J2008-3324 DRWN:HTAGAMI 2008/03/25 CHKD:KAKAHASHI 2008/04/07 APPR:KAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	15:1	METRIC	
	10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	± 0.25	M.HAYASHI	2005/07/28	0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING	
30 OVER	± 0.3	CHECKED BY	DATE	MOLEX INCORPORATED		
		H.HIRATA	2005/07/28	DOCUMENT NO.		
		APPROVED BY	DATE	SD-501912-001		
		M.SASAO	2005/07/28	SHEET NO.		
		MATERIAL NO.	SEE TABLE		1 OF 2	
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		A3				

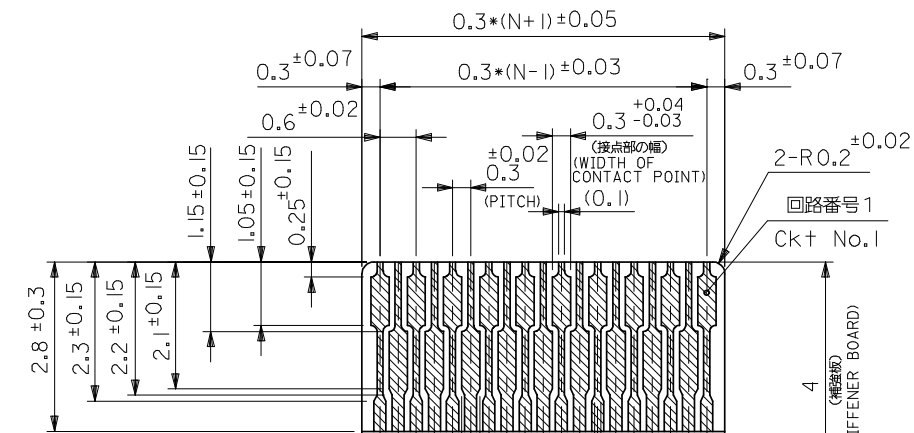


参考基板レイアウト図  
(マウント面)  
(MOUNTING SIDE)

注記 NOTES

- 使用材料 MATFRIAL  
 ハウジング : 耐熱性樹脂 ガラス充填 UL94V-0  
 HOUSING : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0  
 アクチュエータ : 耐熱性樹脂 ガラス充填 UL94V-0  
 ACTUATOR : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0  
 ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ  
 TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.  
 金具 : 銅合金 (t=0.15), ニッケル下地スズメッキ  
 FITTING NAIL : COPPER ALLOY, TIN OVER NICKEL PLATING.  
 ハウジングに黒点がある場合が有りますが、問題はありません。

- ソルダーテール半田付け面、及び金具半田付け面の平坦度 : 0.1mm MAXIMUM.  
 COPLANARITY OF SOLDER TAILS AND FITTING NAILS  
 TO BE 0.1mm MAXIMUM.
- ELV AND RoHS COMPLIANT.



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.2 ± 0.03)  
(THICKNESS: 0.2 ± 0.03)

FPCについて:

打抜き方向は導体側から補強板側を推奨いたします。  
 導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを  
 推奨致します。  
 補強フィルム材質はポリイミドを推奨します。  
 接着剤は熱硬化接着剤を推奨します。

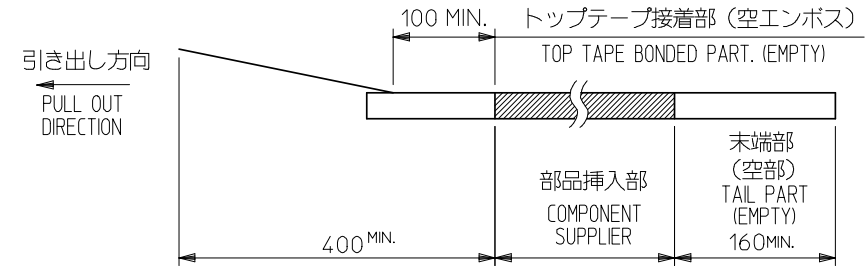
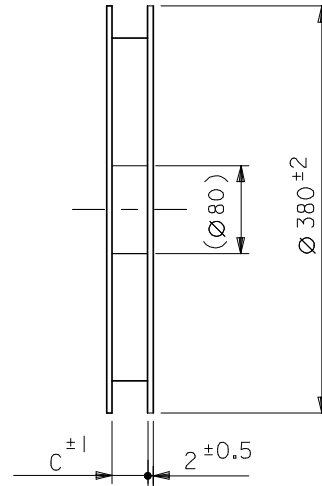
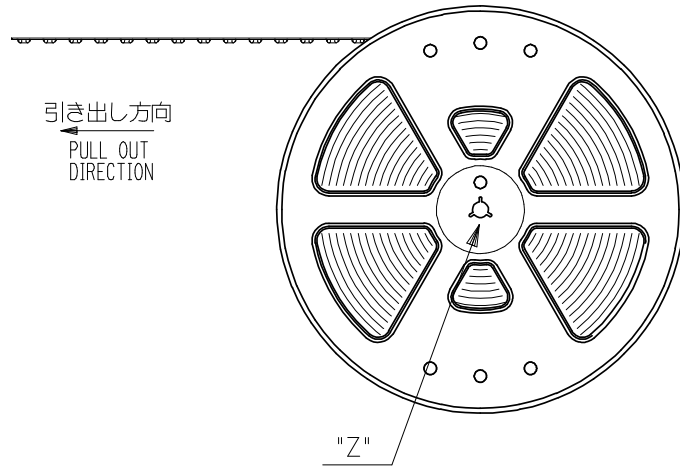
ABOUT FPC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
 RECOMMENDED CONDUCTOR SPEC :  
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

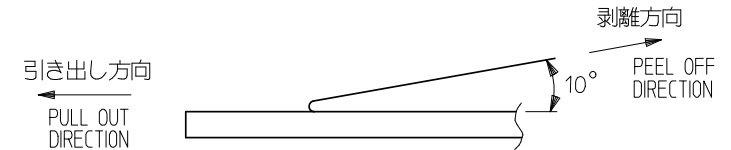
REVISED EC NO: J2008-3324 DRAWN: H. TAGAMI 2008/03/25 CHKD: K. TAKAHASHI 2008/04/07 APPR: K. TAKAHASHI 2008/04/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ----	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING			
		10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/07/28	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/07/28	DOCUMENT NO. SD-501912-001			
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2			
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。  
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量：3000個/リール  
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



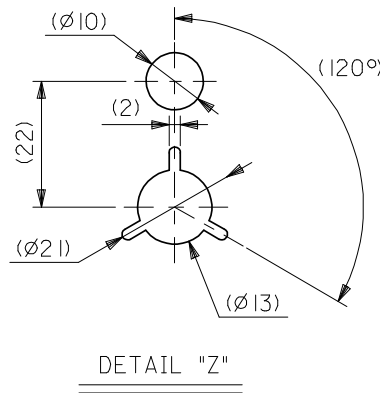
- トップテープの剥離強度：60±35gf (0.25N～0.93N) (剥離方向は下図参照) 尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 65gf±30gf (0.25N～0.93N) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



5. 材料(MATERIAL)

キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYREN)  
 トップテープ (TOP TAPE) : PET, PE, PEF  
 リール(REEL) : ポリスチレン(PS) <リサイクル材を含む>  
 POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>

- C寸法は SHEET 2-4を参照下さい。  
SEE SHEET 2-4(DIMENSION C).
- ELV AND RoHS COMPLIANT.



DETAIL "Z"

REVISED EC NO: J2008-3324 T DRWN:HTAGAMI 2008/03/25 CH'KD:KTAKAHASHI 2008/04/07 APPR:KTAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 501912-**-90	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING			
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11				
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED			
	ANGULAR ±3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501912-002		SHEET NO. 1 OF 4	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

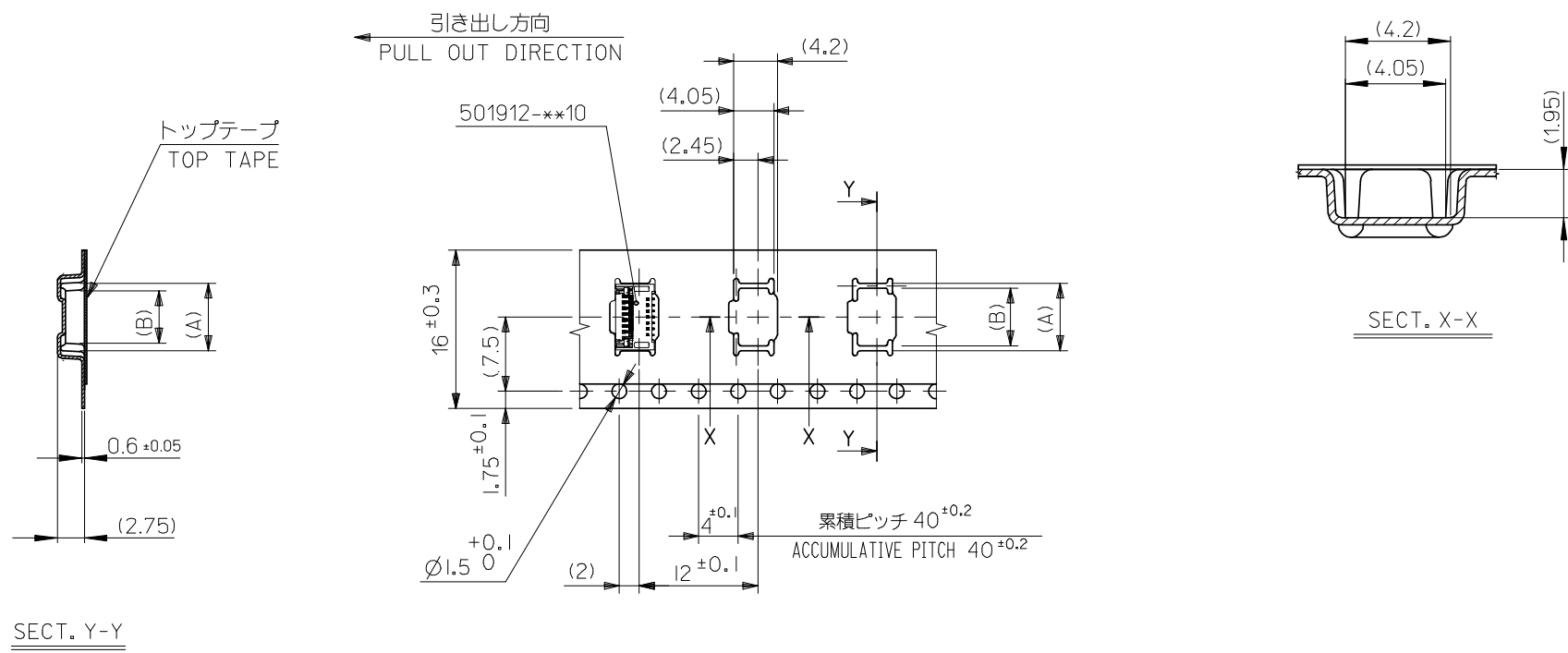
E

D

C

B

A



16 mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE

16	17.5	4.6	6.8	501912-1590	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**90	MODEL No.

REVISED EC NO: J2008-3324 DRAWN: TAGAMI 2008/03/25 CH'KD: TAKAHASHI 2008/04/07 APPR: KITAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/10/11			
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED		
	ANGULAR	± 3 °	MATERIAL NO.	DOCUMENT NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501912-002			

F

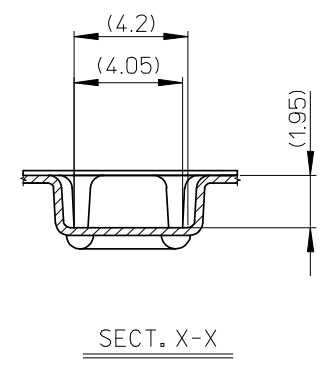
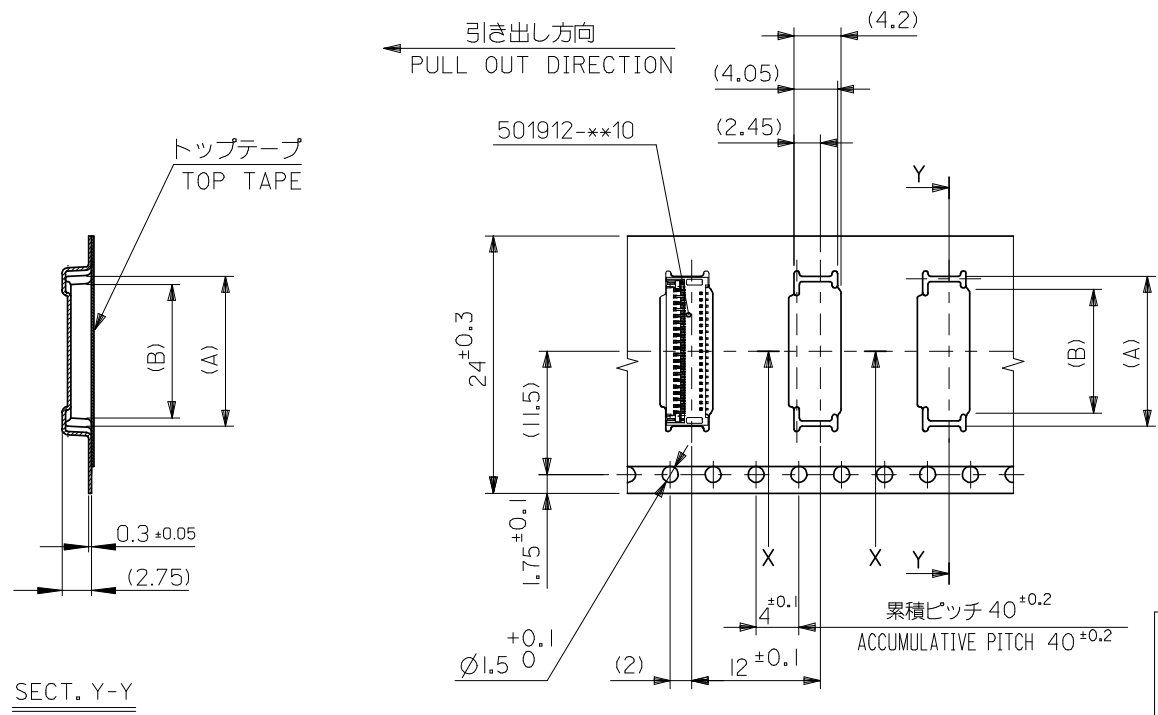
E

D

C

B

A

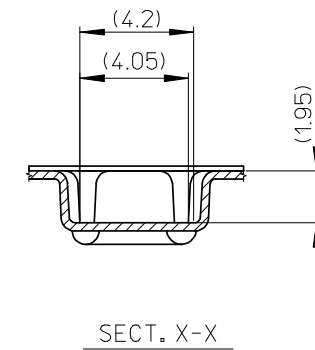
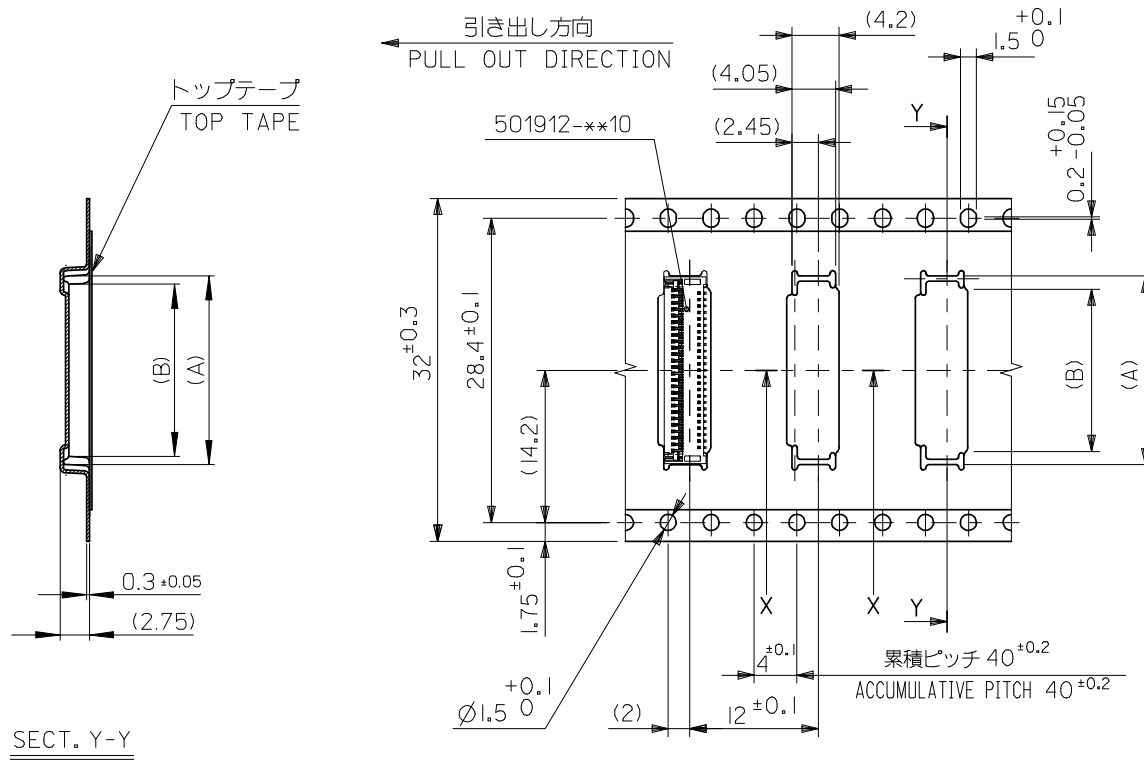


SECT. Y-Y

24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

24	25.5	12.4	14.6	501912-4190	41	
		11.8	14.0	501912-3990	39	
		11.2	13.4	501912-3790	37	
		10.6	12.8	501912-3590	35	
		10.0	12.2	501912-3390	33	
		8.2	10.4	501912-2790	27	
		7.6	9.8	501912-2590	25	
		7.0	9.2	501912-2390	23	
		6.4	8.6	501912-2190	21	
キャリアテープ幅 CARRIER TAPE WIDTH		C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**90	MODEL No.	

REVISED EC NO: J2008-3324 DRWN: HTAGAMI 2008/03/25 CHKD: KTAKAHASHI 2008/04/07 APPR: KTAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING			
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11				
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501912-002		3 OF 4		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE

32	33.5	15.4	17.6	501912-5190	51
		14.2	16.4	501912-4790	47
		13.6	15.8	501912-4590	45
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**-**90	MODEL No.

REVISED EC NO: J2008-3324 T DRWN: H. TAGAMI 2008/03/25 CH'KD: K. TAKAHASHI 2008/04/07 APPR: K. TAKAHASHI 2008/04/07 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING			
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11				
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501912-002		4 OF 4		
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								